H1N400X Series

General Purpose Rectifiers

Features

- High Reliability
- Low Cost
- Low Leakage
- Low forward voltage drop
- High Current Capability
- Glass Passivated Junction

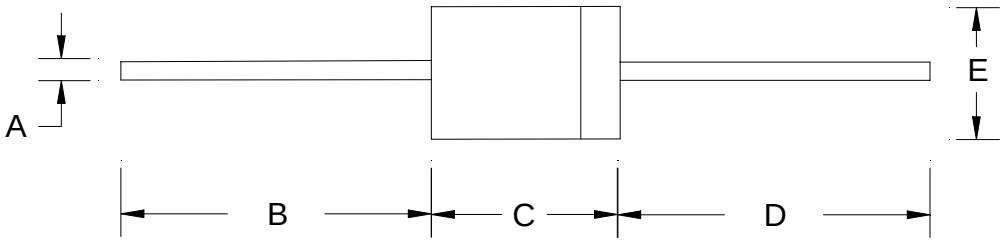
Maximum Ratings & Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load. Drate current by 20%.

Ratings	Symbol	4001	4002	4004	4007	Unit
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	400	1000	V
Maximum RMS voltage	V_{RMS}	35	70	280	700	V
Maximum DC blocking voltage	V_{DC}	50	100	400	1000	V
Maximum average forward recitified current .375”(9.5mm) lead length (Ta=75°C)	I_O	1				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30				A
Typical thermal resistance (Note2)	$R_{\theta JA}$	50				°C/W
Typical junction capacitance (Note1)	C_J	30				pF
Operating & storage temperature Tj	T_{stg}	-50 to +175				°C
Maximum instantaceous forward voltage at 1.0A DC	V_F	1.1				V
Maximum DC reverse current at rated DC blocking voltage @Ta=25°C @Ta=100°C	I_R	5 50				uA
Maximum full load reverse current average full cycle .375”(9.5mm) lead at Tj=75°C		30				uA

Note 1 : Measured at 1MHz and applied reverse voltage of 4.0 volts.
Note 2 : Thermal resistance from junction to ambient 9.5mm lead length.

DO-41 Dimension



DO-41 Molded Plastic Package
HSMC Package Code : L

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0280	0.0340	0.71	0.86	D	1.0000	-	25.40	-
B	1.0000	-	25.40	-	E	0.0800	0.1070	2.00	2.70
C	0.1600	0.2050	4.10	5.20					

Notes : 1.Dimension and tolerance based on our Spec. dated May 28,1998.a
2.Controlling dimension : millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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